



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1701-01 Product Affected: 4DB0226KA3AVG(8) (built in FCCSP-53) Date Effective: 9-May-2017	DATE: 9-Feb-2017	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input checked="" type="checkbox"/> Back Mark <input type="checkbox"/> Date Code <input type="checkbox"/> Other Lot # will have: "B" prefix for SCK, Korea
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Contact: IDT PCN DESK E-mail: pcndesk@idt.com	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Please contact your local sales representative for sample request.
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology <input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Assembly Process <input type="checkbox"/> Equipment <input type="checkbox"/> Material <input type="checkbox"/> Testing <input checked="" type="checkbox"/> Manufacturing Site <input type="checkbox"/> Data Sheet <input type="checkbox"/> Other	<p>This notification is to advise our customers that IDT is adding STATS ChipPAC Korea (SCK) as an alternate assembly facility for parts that are currently assembled at ASEK, Taiwan and ASECL, Taiwan.</p> <p>There is no change to the moisture performance.</p> <p>Attachment I details the qualification results.</p>
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RELIABILITY/QUALIFICATION SUMMARY:
Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1701-01

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding STATS ChipPAC Korea (SCK) as an alternate assembly facility for parts that are currently assembled at ASEK, Taiwan and ASECL, Taiwan.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (ASECL, Taiwan)	Existing Assembly (ASEK, Taiwan)	Alternate Assembly (SCK, Korea)
Die Bump	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag
Mold Compound	KE-G1250FC-20B	KE-G1250FC-20B	KEG-1250FC-K
Substrate	ABF-GX13/E700GR core	ABF-GX13/E700GR core	ABF-GX13/E700GR core
Solder Balls	Sn/Ag1.2/Cu0.50/Ni0.05	Sn/Ag1.2/Cu0.50/Ni0.05	Sn/Ag1.2/Cu0.50/Ni0.05



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ATTACHMENT I - PCN # : A1701-01

Qualification Information and Qualification Data:

Affected Packages: FCCSP-53

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: FCCSP-53

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	-

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test